**Thyristors** logic level

BT169 series

# **GENERAL DESCRIPTION**

Glass passivated, sensitive gate thyristors in a plastic envelope, intended for use in general purpose switching and phase control applications. These devices are intended to be interfaced directly to microcontrollers, logic integrated circuits and other low power gate trigger circuits.

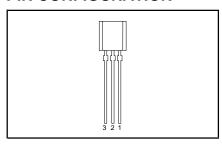
# **QUICK REFERENCE DATA**

SYMBOL	PARAMETER	MAX.	MAX.	MAX.	MAX.	UNIT
$egin{array}{c} egin{array}{c} \egin{array}{c} \egin{array}$	BT169 Repetitive peak off-state voltages	<b>B</b> 200	<b>D</b> 400	<b>E</b> 500	<b>G</b> 600	V
I <sub>T(AV)</sub>	Average on-state current	0.5	0.5	0.5	0.5	Α
I <sub>T(RMS)</sub>	RMS on-state current Non-repetitive peak on-state current	0.8 8	0.8 8	0.8 8	0.8 8	A A

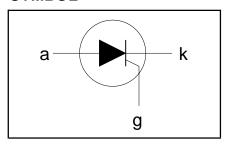
# **PINNING - TO92 variant**

PIN	DESCRIPTION	
1	anode	
2	gate	
3	cathode	

# PIN CONFIGURATION



# **SYMBOL**



# LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.		UNIT		
$V_{DRM}, V_{RRM}$	Repetitive peak off-state voltages		-	<b>B</b> 200 <sup>1</sup>	<b>D</b> 400 <sup>1</sup>	<b>E</b> 500 <sup>1</sup>	<b>G</b> 600 <sup>1</sup>	V
I <sub>T(AV)</sub>	Average on-state current	half sine wave;	-		0	.5		Α
I <sub>T(RMS)</sub> I <sub>TSM</sub>	RMS on-state current Non-repetitive peak on-state current	$T_{lead} \le 83 ^{\circ}\text{C}$ all conduction angles t = 10 ms t = 8.3 ms half sine wave; $T_{i} = 25 ^{\circ}\text{C}$ prior to surge	- - -			.8 3 9		A A A
l²t dl <sub>⊤</sub> /dt	l <sup>2</sup> t for fusing Repetitive rate of rise of on-state current after	$I_{\text{TM}} = 23 \text{ C phorto surge}$ $I_{\text{TM}} = 2 \text{ A; } I_{\text{G}} = 10 \text{ mA;}$ $dI_{\text{G}}/dt = 100 \text{ mA/}\mu\text{s}$	- -			32 60		A²s A/μs
I <sub>GM</sub> V <sub>GM</sub> V <sub>RGM</sub> P <sub>GM</sub> P <sub>G(AV)</sub> T <sub>stg</sub> T <sub>j</sub>	triggering Peak gate current Peak gate voltage Peak reverse gate voltage Peak gate power Average gate power Storage temperature Operating junction temperature	over any 20 ms period	- - - - -40 -		0 1	1 5 5 2 .1 50 25		A V V V C C

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<sup>1</sup> Although not recommended, off-state voltages up to 800V may be applied without damage, but the thyristor may switch to the on-state. The rate of rise of current should not exceed 15 Å/µs.

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# THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
R <sub>th j-lead</sub>	Thermal resistance junction to lead		1	-	60	K/W
R <sub>th j-a</sub>	Thermal resistance junction to ambient	pcb mounted; lead length = 4mm	-	150	-	K/W

# STATIC CHARACTERISTICS

T<sub>i</sub> = 25 °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$\begin{matrix} I_{\text{GT}} \\ I_{\text{L}} \\ I_{\text{H}} \\ V_{\text{T}} \\ V_{\text{GT}} \end{matrix}$	Gate trigger current Latching current Holding current On-state voltage Gate trigger voltage	$V_D$ = 12 V; $I_T$ = 10 mA; gate open circuit $V_D$ = 12 V; $I_{GT}$ = 0.5 mA; $R_{GK}$ = 1 kΩ $V_D$ = 12 V; $I_{GT}$ = 0.5 mA; $R_{GK}$ = 1 kΩ $I_T$ = 1 A $I_T$ = 10 mA; gate open circuit		50 2 2 1.2 0.5	200 6 5 1.35 0.8	μΑ mA MA V
I <sub>D</sub> , I <sub>R</sub>	Off-state leakage current	$ \begin{array}{l} V_{\text{D}} = V_{\text{DRM(max)}}; \ I_{\text{T}} = 10 \ \text{mA}; \ T_{\text{j}} = 125 \ ^{\circ}\text{C}; \\ \text{gate open circuit} \\ V_{\text{D}} = V_{\text{DRM(max)}}; \ V_{\text{R}} = V_{\text{RRM(max)}}; \ T_{\text{j}} = 125 \ ^{\circ}\text{C}; \\ R_{\text{GK}} = 1 \ k\Omega \end{array} $	-	0.3	0.1	MA

# **DYNAMIC CHARACTERISTICS**

 $T_j = 25$  °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
dV <sub>D</sub> /dt	Critical rate of rise of off-state voltage	$V_{DM}$ = 67% $V_{DRM(max)}$ ; $T_j$ = 125 °C; exponential waveform; $R_{GK}$ = 1 kΩ	-	25	-	V/µs
t <sub>gt</sub>	Gate controlled turn-on time	$I_{TM} = 2 \text{ A}; V_D = V_{DRM(max)}; I_G = 10 \text{ mA};$ $I_{G} = 10 \text{ mA};$	-	2	-	μs
t <sub>q</sub>	Circuit commutated turn-off time	$V_D = 67\% \ V_{DRM(max)}; \ T_i = 125 \ ^{\circ}C; \ I_{TM} = 1.6 \ A; \ V_R = 35 \ V; \ dI_{TM}/dt = 30 \ A/\mu s; \ dV_D/dt = 2 \ V/\mu s; \ R_{GK} = 1 \ k\Omega$	-	100	-	μs

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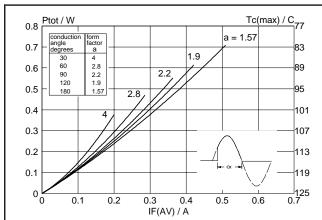


Fig.1. Maximum on-state dissipation,  $P_{tot}$ , versus average on-state current,  $I_{T(AV)}$ , where  $a = form\ factor = I_{T(RMS)}/I_{T(AV)}$ .

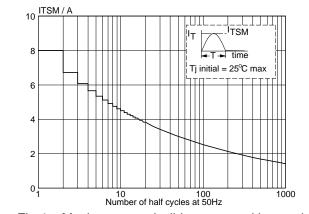


Fig.4. Maximum permissible non-repetitive peak on-state current  $I_{TSM}$ , versus number of cycles, for sinusoidal currents, f = 50 Hz.

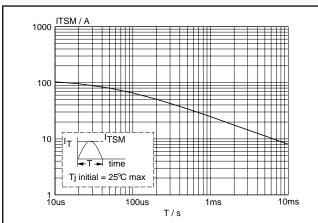


Fig.2. Maximum permissible non-repetitive peak on-state current  $I_{TSM}$ , versus pulse width  $t_p$ , for sinusoidal currents,  $t_p \le 10$ ms.

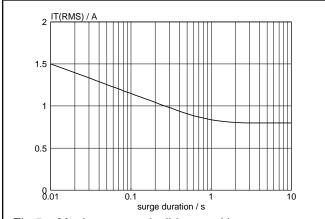


Fig.5. Maximum permissible repetitive rms on-state current  $I_{T(RMS)}$ , versus surge duration, for sinusoidal currents, f = 50 Hz;  $T_{lead} \le 83$  °C.

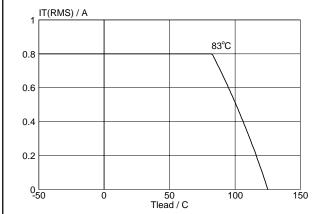
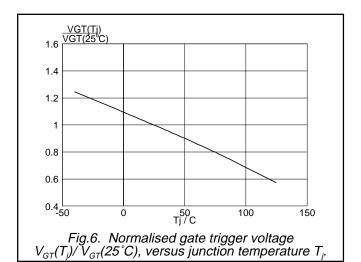
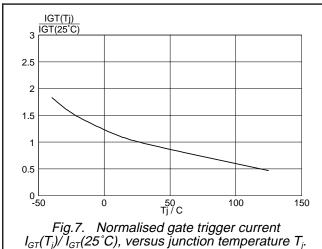
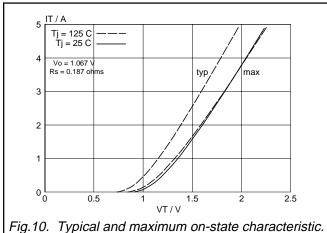


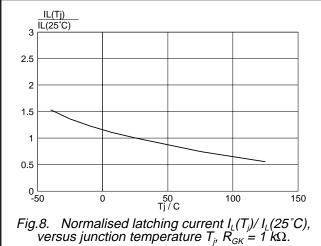
Fig.3. Maximum permissible rms current  $I_{T(RMS)}$ , versus lead temperature,  $T_{lead}$ .



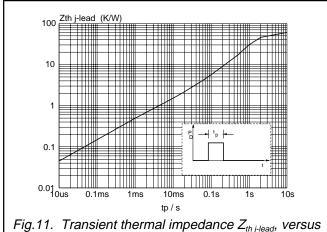
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pulse width  $t_p$ .

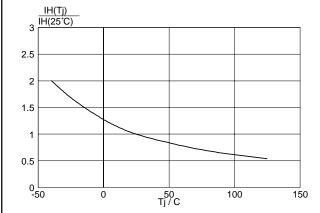


Fig.9. Normalised holding current  $I_H(T_j)/I_H(25^{\circ}C)$ , versus junction temperature  $T_j$ ,  $R_{GK}=1$  k $\Omega$ .

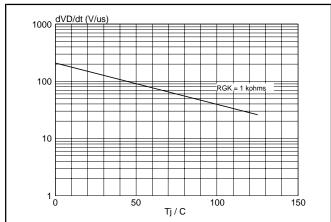
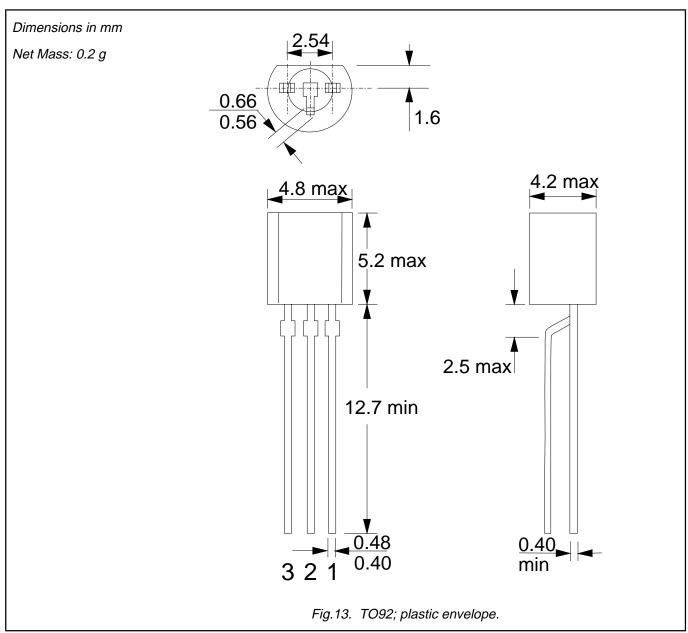


Fig.12. Typical, critical rate of rise of off-state voltage,  $dV_D/dt$  versus junction temperature  $T_{j\cdot}$ 

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# **MECHANICAL DATA**



Notes
1. Epoxy meets UL94 V0 at 1/8".

Philips Semiconductors Product specification

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# **DEFINITIONS**

Data sheet status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limitin arrealises	

### Limiting values

Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

#### **Application information**

Where application information is given, it is advisory and does not form part of the specification.

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